Last update: 2015.12.25 No.RLP-K-HTS-0001-9

Specification

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

Style: RLP16,20,32,63, MLP20,63

RoHS COMPLIANCE ITEM
Halogen and Antimony Free

Product specification contained in this specification are subject to change at any time without notice If you have any questions or a Purchasing Specification for any quality Agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya

Note: Stock conditions

Temperature: $+5^{\circ}$ C ~ $+35^{\circ}$ C Relative humidity: 25% ~ 75%

The period of guarantee: Within 2 year from shipment by the company.

Solderability shall be satisfied.

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1. Scope

1.1 This specification covers the detail requirements for metal-plate chip resistor; low ohm, style of RLP16, 20, 32, 63, MLP20,63.

1.2 Applicable documents

JIS C 5201-1: 1998, JIS C 5201-8: 1998, JIS C 5201-8-1: 1998

IEC60115-1: 1999, IEC60115-8: 1989 Amendment 1: 1992, IEC60115-8-1: 1989

2. Classification

Type designation shall be the following form.

(Example)

1 Metal - plate chip resistor; low ohm

2 Size

3 Temperature coefficient of resistance

N	±70×10 ⁻⁶ /°C
K	±100×10 ⁻⁶ /°C
-(Dash)	±150×10 ⁻⁶ /°C

- 4 Rated resistance
- 5 Tolerance on rated resistance
- 6 Packaging form

3. Rating

3.1 The ratings shall be in accordance with Table-1.

Table_1(1)

	$Iable_{I}(I)$											
Style	Rated dissipation	Rated current	Temperature	coefficient of	Rated resistance	Tolerance on rated						
Otylo	(W)	(A)	resistance	(10 ⁻ %°C)	$(m\Omega)$	resistance						
		8.1	K	100	5							
RLP16	0.33	0.1	N	±70	3							
INLFIO	0.55	5.7	K	100	10							
		5.7	N	±70	10							
		11.1	K	100	4							
		11.1	N	±70	4							
								10.0	K	100	5	
		10.0	N	±70	3	F(±1%) J(±5%)						
		9.1	K	100	6							
RLP20	0.5	9.1	N	±70	U							
INLFZU	0.5	7.9	K	100	8							
		7.9	N	±70	°							
		7.4	K	100	9							
		7.4	N	±70	9							
		7.0	K	100	10							
		7.0	N	±70	10							
MI DOO	1.0	10.0	K	100	10							
MLP20	1.0	10.0	N	±70	10							

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Issue: KAMAYA ELECTRIC CO., LTD. Research & Development Department HOKKAIDO Research center Last update: 2015.12.25



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Table-1(2)

1abic-1(2)							
Style	Rated dissipation	Rated current	Temperature coefficient of		Rated resistance $(m\Omega)$	Tolerance on rated	
Otylo	(W)	(A)		resistance (10 ⁻⁶ / °C)		resistance	
		31.6	-(Standard)	±150	1		
		31.0	K	±100	ı		
		22.3	K	±100	2		
		22.3	N	±70	2		
		18.2	K	±100	3		
		10.2	N	±70	3		
		15.8	K	±100	4		
		13.6	N	±70	4		
		14.1	K	±100	5		
		14.1	N	±70	5		
		12.0	K	±100	6	F(±1%) J(±5%)	
		12.9	N	±70	· · ·		
RLP32	1.0	11.0	K	±100	7		
KLF32	1.0	11.9	N	±70	/		
		11.1	K ±100	0			
		11.1	N	±70	0		
		10 F	K	±100	9		
		10.5	N	±70	9		
		10	K	±100	10		
		10	N	±70	10		
		0.1	K	±100	10		
		9.1	N	±70	12		
		0.7	K	±100	12		
		8.7	N	±70	13		
		0.1	K	±100	15		
		8.1	N	±70	15		

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Table-1(3)

			Table-			1		
Style	Rated dissipation	Rated current	Temperature resistance	coefficient of	Rated resistance	Tolerance on rated resistance		
	(VV)	(A)	-(Standard)	±150	(m Ω)	resistance		
	2.0	44.7			1			
			K	±100		-		
		22.3	K	±100	2			
			N	±70		-		
		18.2	K	±100	3			
			N	±70		-		
		15.8	K	±100	4			
			N	±70		 -		
		14.1	K	±100	5			
			N	±70	•			
		12.9	K	±100	6			
RLP63		12.0	N	±70		F(±1%)		
I (LI OO	1.0	11.9	K	±100	7	J(±5%)		
	1.0	11.9	N	±70	,			
		11.1	K	±100	8			
		11.1	N	±70	0			
		40.5	K	±100	0			
		10.5	N	±70	9			
		40	K	±100	40			
		10	N	±70	10			
		0.4	K	±100	40			
		9.1	N	±70	12			
		8.1	K	±100				
			N	±70	15			
					K	100		
		63.2	N	±70	0.5	J(±5%)		
			K	100				
		36.5	N	±70	1.5			
			K	100				
		31.6	N	±70	2			
			K	100		-		
		28.2	N	±70	2.5			
			K	100		-		
		25.8	N	±70	3			
			K	100		-		
		22.3	N	±70	4			
MLP63	2.0	a -	K	100	_	F(±1%)		
		20	N	±70	5	J(±5%)		
		10.0	K	100	_	1		
		18.2	N	±70	6			
		40.0	K	100	_	1		
		16.9	N	±70	7			
		4= 0	K	100	_	1		
		15.8	N	±70	8			
		44.5	K	100	•	1		
		14.9	N	±70	9			
		444	K	100	40	1		
		14.1	N	±70	10			

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Table-1(4)

10.000						
Style	Isolation voltage (V)	Category temperature range (°C)				
RLP16						
RLP20						
MLP20	100	EE .15E				
RLP32	100	_55~+155 				
RLP63						
MLP63						

3.2 Climatic category

55/155/56 Lower category temperature –55 °C

Upper category temperature +155 °C

Duration of the damp heat, steady state test 56days

3.3 Stability class

5% Limits for change of resistance:

-for long–term tests $\pm 5\%$ -for short–term tests $\pm 1\%$

3.4 Derating

The derated values of dissipation at temperature in excess of 70 °C shall be as indicated by the following curve.

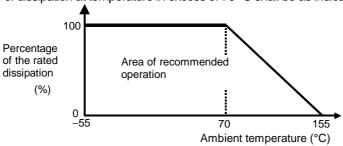


Figure-1 Derating curve

3.5 Rated voltage

d.c. or a.c. r.m.s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

E: Rated voltage (V)

P: Rated dissipation (W)

R: Rated resistance (
$$\Omega$$
)

3.6 Rated current

The rated current calculated from the square root of the quotient of the rated resistance and the rated dissipation.

I: Rated current (A)
P: Rated dissipation (W)
R: Rated resistance (
$$\Omega$$
)

The rated current shall be corresponding to rated voltage.

4. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

Symbol	Packaging form		Packaging form Standard packaging quantity / units	
TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	RLP16, 20, 32, MLP20
TE	Embossed taping	12mm width, 4mm pitches	4,000 pcs.	RLP63, MLP63

KMY

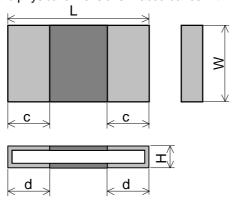
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5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure-2 and Table-3.



Figure–2 Table–3(1)

Unit: mm

Style	Rated resistance (mΩ)	L	W	Н	С	d
DI DAG	5	4.0.04	0.0.04	0.35±0.10	0.2±0.1	0.6±0.1
RLP16	10	1.6±0.1	0.8±0.1	0.3±0.1	0.2±0.1	0.3±0.1
	4			0.35±0.10	0.3±0.1	0.7±0.2
	5			0.35±0.10	0.3±0.1	0.6±0.2
DI DOO	6			0.35±0.10	0.3±0.1	0.47±0.20
RLP20	8	2.0±0.15	1.25±0.15	0.22±0.10	0.3±0.1	0.6±0.2
	9			0.22±0.10	0.3±0.1	0.52±0.20
	10			0.22±0.10	0.3±0.1	0.47±0.20
MLP20	10			0.22±0.10	0.3±0.1	0.47±0.20
	1			0.32±0.15	1.1±0.25	1.1±0.25
	2			0.32±0.15	0.5±0.25	0.5±0.25
	3			0.35±0.10	0.7±0.25	1.3±0.25
	4			0.35±0.10	1.1±0.25	1.1±0.25
	5		1.6±0.15	0.35±0.10	1.0±0.25	1.0±0.25
	6	3.2±0.15		0.35±0.10	0.85±0.25	0.85±0.25
RLP32	7			0.35±0.10	0.7±0.25	0.7±0.25
	8			0.35±0.10	0.6±0.25	0.6±0.25
	9			0.3±0.1	0.75±0.25	0.75±0.25
	10			0.28±0.10	0.5±0.25	0.5±0.25
	12			0.22±0.10	0.65±0.25	0.65±0.25
	13			0.22±0.10	0.65±0.25	0.65±0.25
	15			0.22±0.10	0.5±0.25	0.5±0.25
	1		3.2±0.25	0.38±0.15	2.2±0.25	2.2±0.25
	2			0.38±0.15	1.1±0.25	1.1±0.25
	3			0.45±0.15	2.2±0.25	2.2±0.25
	4			0.35±0.15	2.2±0.25	2.2±0.25
	5			0.34±0.15	1.95±0.25	1.95±0.25
RLP63	6	6.3±0.25		0.34±0.15	1.75±0.25	1.75±0.25
INLE 03	7	0.5±0.25	3.1±0.25	0.35±0.15	1.4±0.25	1.4±0.25
	8			0.35±0.15	1.1±0.25	1.1±0.25
	9			0.35±0.15	0.8±0.25	0.8±0.25
	10			0.23±0.15	1.75±0.25	1.75±0.25
	12			0.23±0.15	1.4±0.25	1.4±0.25
	15			0.23±0.15	0.95±0.25	0.95±0.25

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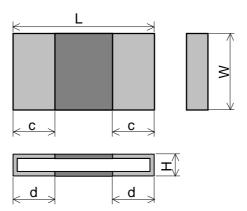


Table-3(2) Unit: mm

		T	1	011111111111111111111111111111111111111		
Style	Rated resistance (m Ω)	L	W	H	С	d
	0.5			0.58±0.15	2.2±0.25	2.2±0.25
	1.5			0.38±0.15	1.5±0.25	1.5±0.25
	2			0.58±0.15	2.2±0.25	2.2±0.25
	2.5		3.1±0.25	0.45±0.15	2.4±0.25	2.4±0.25
	3	6.3±0.25		0.45±0.15	2.2±0.25	2.2±0.25
MLP63	4			0.34±0.15	2.2±0.25	2.2±0.25
IVILFOS	5			0.51±0.15	1.1±0.25	1.1±0.25
	6			0.5±0.15	1.1±0.25	1.1±0.25
	7			0.5±0.15	0.6±0.25	0.6±0.25
	8			0.35±0.15	1.1±0.25	1.1±0.25
	9			0.35±0.15	0.8±0.25	0.8±0.25
	10			0.35±0.15	0.5±0.25	0.5±0.25

5.2 Net weight (Reference)

5.2 Net Weight (Neierence)								
Style	Rated resistance (m Ω)	Net weight (mg)						
RLP16	5	2						
KLP10	10	2						
RLP20	4 to 10	3						
MLP20	10	3						
	1	12						
	2	11						
	3	11						
	4	12						
	5	11						
	6	11						
RLP32	7	11						
	8	10						
	9	9						
	10	9						
	12	8						
	13	7						
	15	6						



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5.2 Net weight (Reference)

Style	Rated resistance (m Ω)	Net weight (mg)
	1	50
	2 3	42
	3	57
	4	43
	5	43
DI DCo	6	41
RLP63	7	42
	8	41
	9	40
	10	30
	12	26
	15	26
	0.5	90
	1.5	47
	2	77
	2.5	63
	3 4	63
MLP63	4	48
IVILFOS	5	64
	6	55
	7	55
	8	43
	9	40
	10	41

6. Marking

The Rated resistance of RLP16 should not be marked standard.

6.1 RLP63, MLP63

The rated resistance shall be marked in 4 characters consisting of 3 figures and a letter and marked on over coat side.

(Example) "R010"
$$\rightarrow$$
 0.01 [Ω] \rightarrow 10 [m Ω]

"1L50"
$$\rightarrow$$
 0.0015 [Ω] \rightarrow 1.5 [m Ω]

6.2 RLP20, 32, MLP20

The rated resistance shall be marked in combination of two figures and underlines and marked on over coat side.

(Example) "
$$\underline{05}$$
" \rightarrow 0.005 [Ω] \rightarrow 5 [m Ω]

"
$$\underline{10}$$
" \rightarrow 0.01 [Ω] \rightarrow 10 [m Ω]



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7. Performance

7.1 The standard condition for tests shall be in accordance with Sub-clause 4.2, JIS C 5201–1: 1998.

7.2 The performance shall be satisfied in Table-4.

Table-4(1)

No.	Test items		Condition of test	. ,	201–1)		Performance requirements
1	Visual examination	Sub-claus		`	,		As in 4.4.1
'	Viodal Grainii Idae.		oy visual examin	ation			The marking shall be legible, as
		O TOOR OUT	sy viodai ortai i iii	icación in			checked by visual examination.
2	Dimension	Sub-claus	se 4 4 2				As specified in Table-3 of this
-		Oub oldad	00 1. 1. <u>L</u>				specification.
	Resistance	Resistanc	e value shall be	e measu	red by m	nountina	As in 4.5.2
			ate of the followi			3	The resistance value shall
			$h \rightarrow k a$	Ü			correspond with the rated
		Current		rrent			resistance taking into account the
		terminal	o <u>↑</u> ter	minal			specified tolerance.
			√ oltage terminal	<u> </u>	:Coppe	r clad resist	
		V	ollage terminal				
			D. C. C.	1	Un	it:mm	
		Style	Resistance	а	b	С	
			value(mΩ)	0.0	0.0		
		RLP16	5 10	0.6 1.0	0.8	0.8	
		RLP20	4 to 10	0.8	0.95	1.35	
		MLP20	10	0.8	0.95	1.35	
			1	1.0	1.45		
			2	2.1	0.9		
		RLP32	3	0.8	1.55	1.7	
			5 and 6	1.0 1.4	1.45 1.25		
			7 to 15	2.1	0.9		
			1	1.5	3.0	4.0	•
			2	4.0	1.8	4.0	
		RLP63	3, 4	1.8	2.9	1	
		I NEI OO	5	2.4	2.6	3.5	
			6 to 15	4.0	1.8		
		NAI DOG	0.5,2 to 4	1.8	2.9	0.5	1
		MLP63	1.5, 5 to 10	4.0	1.8	3.5	
		Thickness	of copper clad:	0.035mr	•		
		4-Terminal method					
		Measurement current: 1(A)					
		Note: The measuring apparatus corresponding to				_	
		DC Low-ohm Mater (1A) of AX-1152D for ADEX					
		CORPORATION.					
3	Voltage proof	Sub-claus					No breakdown or flash over
		Method: 4.6.1.4(See Figure–5)					
		Test voltage: Alternating voltage with a peak value					
		of 1.42 times the insulation voltage. Duration: 60 s±5 s					
			resistance				R≥1 GΩ
			ge: Insulation vol	tage			1 1 032
		Duration:		wgc			
		Duration:	i min.				



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Table-4(2)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
4	Solderability	Sub-clause 4.17	As in 4.17.4.5
		Without aging	The terminations shall be covered
		Flux: The resistors shall be immersed in a	with a smooth and bright solder
		non-activated soldering flux for 2 s.	coating.
		Bath temperature: 235 °C±5 °C	
		Immersion time: 2 s±0.5 s	
5	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: RLP16: Figure–3–1	
	Overload	RLP20, MLP20 Figure-3-2	
	(in the mounted state)	RLP32 Figure–3–3	
		RLP63, MLP63 Figure-3-4	
		Sub-clause 4.13	
		The applied voltage shall be 2.5 times the rated	
		voltage or the current corresponding to.	
		Duration: 2 s	NI - 2-9-In decree
		Visual examination	No visible damage
	Calcord resistance of the	Resistance	ΔR ≤ ±1%
	Solvent resistance of the	Sub-clause 4.30	Legible marking
	marking	Solvent: 2-propanol	
		Solvent temperature: 23 °C±5 °C	
		Method 1	
		Rubbing material: cotton wool	
		Without recovery	
6	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure–4	
	Bound strength of the end	Sub-clause 4.33	
	face plating	Bent value: 3mm(RLP16, 20, 32, MLP20)	
		1 mm(RLP63, MLP63)	
		Resistance	ΔR ≤ ±1%
	Final measurements	Sub-clause 4.33.6	
		Visual examination	No visible damage

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Table-4(3)

	Iable—4(3)							
No	Test	t iten	ns	Condition of test (JIS C 5201–1)	Performance requirements			
7	Resistance heat	to	soldering	Sub-clause 4.18 (JEITA RC-2144 2.3.2) Substrate material: Epoxide woven glass Test substrate: Figure-3-1 T ₁ :Pre-heat minimum temp.:150±5 °C T ₂ :Pre-heat maximum temp.:180±5 °C T ₃ :Soldering temp.:220 °C T ₄ :Pre-heat duration:120±5 s t ₂ :Soldering duration:60 to 90 s t ₃ :Peak duration(T ₄ -5°C):20 to 40 s Pre-reflow soldering: 1 time (Initial measurements) Reflow soldering: 3 times				
	Component resistance		solvent	Visual examination Resistance Sub-clause 4.29 Solvent: 2-propanol Solvent temperature: 23 °C±5 °C Method 2 Recovery: 48 h Visual examination Resistance	No visible damage $\Delta R \leq \pm 1\%$ No visible damage $\Delta R \leq \pm 1\%$			
8	Mounting Adhesion			Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3-1 Sub-clause 4.32				
	Rapid chang	e ter	mperature	Force: 5 N Duration: 10 s±1 s Visual examination Sub–clause 4.19 Lower category temperature:–55 °C Upper category temperature:+155 °C Duration of exposure at each temperature: 30 min. Number of cycles: 5 cycles. Visual examination	No visible damage No visible damage			
					No visible damage $\Delta R \le \pm 1\%$			



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Table-4(4)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
9	Climatic sequence	Sub-clause 4.23	
	-Dry heat	Sub-clause 4.23.2	
		Test temperature: +155 °C	
		Duration: 16 h	
	-Damp heat, cycle	Sub-clause 4.23.3	
	(12+12hour cycle)	Test method: 2	
	First cycle	Test temperature: 55 °C	
		[Severity(2)]	
	-Cold	Sub-clause 4.23.4	
		Test temperature –55 °C	
		Duration: 2h	
	-Damp heat, cycle	Sub-clause 4.23.6	
	(12+12hour cycle)	Test method: 2	
	Remaining cycle	Test temperature: 55 °C	
		[Severity (2)]	
	DO Israel	Number of cycles: 5 cycles	
	-D.C. load	Sub-clause 4.23.7	
		The applied current shall be the rated current. Duration: 1 min.	
		Visual examination	No visible damage
		Resistance	ΔR ≤ ±5 %
10	Mounting	Sub-clause 4.31	
.0	i vioanang	Substrate material: Epoxide woven glass	
		Test substrate: RLP16: Figure–3–1	
		RLP20, MLP20 Figure-3-2	
		RLP32 Figure-3-3	
		RLP63, MLP63 Figure-3-4	
	Endurance at 70 °C	Sub-clause 4.25.1	
		Ambient temperature: 70 °C±2 °C	
		Duration: 1000 h	
		The current shall be applied in cycles of 1.5 h on	
		and 0.5 h.	
		The applied current shall be the rated current	
		Examination at 48 h, 500 h and	
		1000 h:	No visible damage
		Visual examination	$\Delta R \le \pm 5\%$
44	B.A	Resistance	ZI (= ±0 /0
11	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
	Variation of resistance with	Test substrate: Figure–3–1 Sub–clause 4.8	As in Table–1
	temperature		/ WIII IGDIC I
	toporataro	+20 °C / +155 °C	

KMY Drawing No: RLP-K-HTS-0001 /9

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

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Table-4(5)

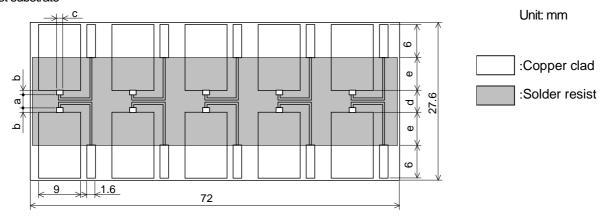
NI.	To at it area	0 10 (1 (10 0 5004 4)	Danfarra and a manufirm and a
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
12	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure–3–1	
	Damp heat, steady state	Sub-clause 4.24	
		Ambient temperature: 40 °C±2 °C	
		Relative humidity: 93 ⁺² / ₋₃ %	
		Without current applied.	No visible demage
		Visual examination	No visible damage Legible marking
			Legible marking ΔR≤±5%
		Resistance	ΔR ≤ ±3%
13	Dimensions (detail)	Sub-clause 4.4.3	As in Table-4
	Mounting	0.1	
	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
	Endurance at upper	Test substrate: Figure–3–1	
	category temperature	Sub-clause 4.25.3	
	category temperature	Ambient temperature:155 °C±2 °C Duration: 1000 h	
		Examination at 48 h, 500 h and	
		1000 h:	
		Visual examination	No visible damage
		Resistance	ΔR ≤ ±5%

KMY Drawing No: RLP-K-HTS-0001 /9

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

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8. Test substrate



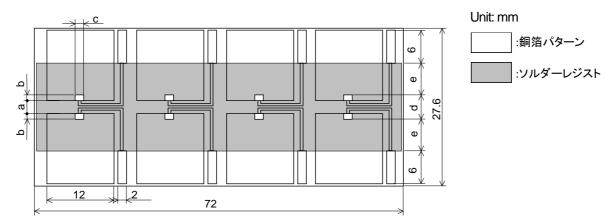
	1	1		1		
Style	Rated resistance (m Ω)	а	b	С	d	е
RLP16	5	0.6	8.0	0.0	2.2	6.2
KLP10	10	1.0	0.6 0.8 1.0 0.6 0.8 0.95 1.35 2.7 1.0 1.45 2.1 0.9 0.8 1.55 1.0 1.45 1.4 1.25 2.1 0.9 1.5 3.05 4.0 1.8 1.8 2.9 2.4 2.6 4.0 1.8 1.8 2.9 1.8 2.9	2.2	0.2	
RLP20	4 to 10	0.0	0.05	4 OF	2.7	E OE
MLP20	10	0.6	.0 1.45		2.7	5.95
	1	1.0	1.45		3.9	5.35
	2	2.1	0.9			
DI Daa	3	0.8	1.55	17		
RLP32	4	1.0	1.45	1.7		
	5 and 6	1.4	1.25			
	7 to 15	2.1	0.9			
	1	1.5	3.05			
	2	4.0	1.8			
RLP63	3, 4	1.8	2.9	3.5	7.6	3.5
	5	2.4	2.6			
	6 to 15	4.0	1.8			
MI Dea	0.5, 2 to 4	1.8	2.9	2.5	76	2.5
MLP63	1.5, 5 to 10	4.0	1.8	3.5	7.6	3.5

Figure-3-1 RLP16, 20, 32, 63, MLP20, 63TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm

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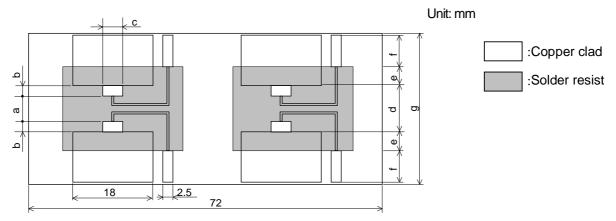


Style	Rated resistance (m Ω)	а	b	С	d	е
RLP20	4 to 10	0.8	0.95	1.35	2.7	5.95
MLP20	10	0.6	0.95	1.33	2.1	5.95

Figure-3-2 RLP20, MLP20 TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm



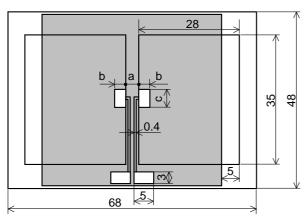
Style	Rated resistance (m Ω)	а	b	С	d	е	f	g	
RLP32	1	1.0	1.45				11.68	39	
	2	2.1	0.9				6.0	27.6	
	3 0.8 1.55 1.7 3.9	5.35	0.0	27.0					
	4	1.0	1.45	1.7	3.9 5.3	3.9	5.55	11.68	39
	5 and 6	1.4 1.25				6.0	27.6		
	7 to 15	2.1	0.9				0.0	27.0	

Figure-3-3 RLP32 TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.07mm

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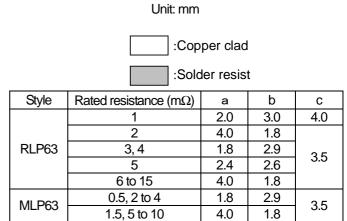


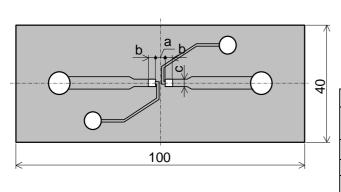
Figure-3-4 RLP63, MLP63 TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.07mm

Remark: In the case of connection by connector, the connecting terminals are gold plated.

However, the plating is not necessary when the connection is made by soldering.



Unit: mm					
:Copper clad					
:Solder resist					

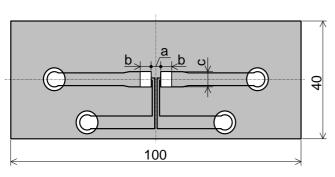
Style	Rated resistance (m Ω)	а	b	С	
RLP16	5	0.6	0.8	0.0	
KLPIO	10	1.0	0.6	0.9	
RLP20	4 to 10	0.8	0.95	1.35	
MLP20	10	0.0	0.33	1.00	
	1	1.0	1.45		
	2	2.1	0.9		
RLP32	3	0.8	1.55	1.7	
KLF32	4	1.0	1.45	1.7	
	5 and 6	1.4	1.25		
	7 to 15	21	0.9		

RLP16, 20, 32, MLP20 BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

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Unit: mm					
	:Copper clad				
	:Solder resist				

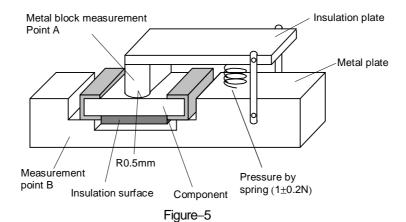
Style	Rated resistance (m Ω)	а	b	С	
	1	1.5	3.05	4.0	
	2	4.0	1.8		
RLP63	3, 4	1.8	2.9	3.5	
	5		2.6	3.5	
	6 to 15	4.0	1.8		
MI Dea	0.5, 2 to 4	1.8	2.9	3.5	
MLP63	1.5, 5 to 10		1.8	3.5	

RLP 63, MLP63 BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

Figure 4

Remark. Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm



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9. Taping

- 9.1 Applicable documents JIS C 0806-3: 1999, EIAJ ET-7200B: 2003
- 9.2 Taping dimensions
- 9.2.1 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-6 and Table-5.

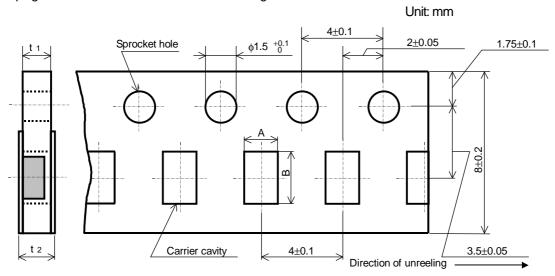


Figure-6

	Unit: mm				
Style	Α	В	t 1	t 2	
RLP16	1.15±0.15	1.9 ± 0.2	0.6±0.1	0.8max.	
RLP20	1.65±0.15	2.5±0.2	0.6±0.1	0.8max.	
MLP20	1.00±0.10	2.5±0.2	0.0±0.1	U.omax.	
RLP32	2.00±0.15	3.6±0.2	0.6±0.1	0.8max.	

9.2.2 Embossed taping (12mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-7 and Table-6.

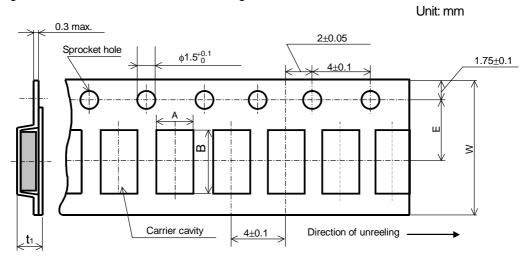


Figure-7

	Unit: mm				
Style	Α	В	W	E	t 1
RLP63	3.6±0.2	6.9+0.2	12.0±0.3	5.5±0.05	1.1±0.15
MLP63	3.0±0.2	0.9±0.2	12.0±0.3	5.5±0.05	1.1±0.15

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Title: METAL-PLATE CHIP RESISTOR; LOW OHM

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- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following RLP16, 20, 32, MLP20: Figure–8, RLP63, MLP63: Figure–9.
- 6). When the tape is bent with the minimum radius for (RLP16, 20, 32, MLP20: 25mm, RLC63, MLP63: 30mm) the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.

 The maximum number of missing components shall be one or 0.1%, whichever is greater.

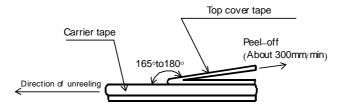


Figure-8

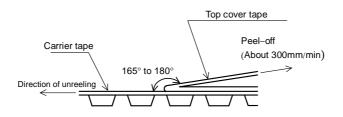


Figure-9

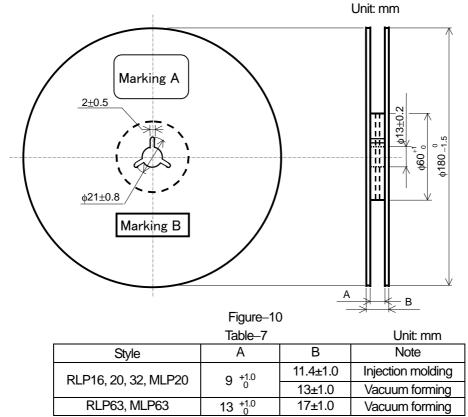
KMY Drawing No: RLP-K-HTS-0001 /9

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

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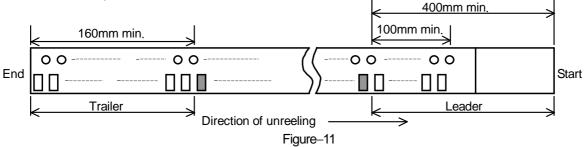
9.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure–10 and Table–7. Plastic reel (Based on EIAJ ET–7200B)



Note: Marking label shall be marked on a place of Marking A or two place of Marking A and B.

9.4 Leader and trailer tape.



10. Marking on package

The label of a minimum package shall be legibly marked with follows.

10.1 Marking A

(1) Classification

(Style, Temperature coefficient of resistance, Rated resistance, Tolerance on rated resistance, Packaging form)

(2) Lot number (3) Quantity (4) Manufacturer's name or trade mark (5) Others

10.2 Marking B (KAMAYA Control label)

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Kamaya:

 RLP63KR010FTE
 RLP32KR005JTP
 RLP32KR015FTP
 RLP32KR002FTP
 RLP20KR010FTP
 RLP32KR003FTP

 RLP32KR005FTP
 RLP32KR010JTP
 RLP63KR002FTE
 RLP32KR004FTP
 RLP32KR010FTP
 RLP32KR010FTP
 RLP32KR008FTP

 RLP63KR005FTE
 RLP16KR010FTP
 RLP32KR007FTP
 RLP32KR015JTP
 RLP32KR015JTP

Walsin:

RLP32KR003JTP